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(54) Title: ETCH MASKS BASED ON TEMPLATE-ASSEMBLED NANOCLUSTERS

Thermally Oxidised SI

At Plasma Etch

Anisotropic Si etching

Thermally Oxidised SI

Cluster and Aufli wires

Cluster and Aufli wires

Aufli wires after selective etch

Motallised and Oxidised SI

Aufli wires after selective etch

atomic clusters (e.g. antimony or bismuth) into V-grooves. These structures, preferably in the form of nanowires, are used as etching masks for the subsequent etching of the substrate. In an embodiment the V-grooves are metallised (e.g. with titanium or gold) prior





atomic clusters (e.g. antimony or bismuth) into V-grooves. These structures, preferably in the form of nanowires, are used as etching masks for the subsequent etching of the substrate. In an embodiment the V-grooves are metallised (e.g. with titanium or gold) prior masks for the subsequent etching of the substrate. In an embodiment the V-grooves are metallised (e.g. with titanium or gold) prior to the deposition of the clusters. In this case the use of the nanostructures (e.g. antimony or bismuth) as an etching mask results in the formation of nanostructures of the underlying metal (e.g. titanium or gold). In this way the dimensions of the nanowires are transferred into the underlying metal film and the method allows fabrication of nanowires from materials (e.g. titanium or gold) that cannot be deposited as clusters.

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